

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Rajasekaran SWAMINATHAN	12/23/2008
RECEIVING PARTY DATA	
Name:	Intel Corporation
Street Address:	2200 Mission College Boulevard
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95052
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12343341
CORRESPONDENCE DATA	
Fax Number:	(310)556-7984
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	310-556-7983
Email:	gbell@ipmatters.com
Correspondent Name:	Konrad Raynes and Victor LLP
Address Line 1:	315 S. Beverly Dr.
Address Line 2:	Suite 210
Address Line 4:	Beverly Hills, CALIFORNIA 90212
ATTORNEY DOCKET NUMBER:	P27422 (77.213)
NAME OF SUBMITTER:	Geoffrey Bell
Total Attachments: 2 source=P27422_Assign#page1.tif source=P27422_Assign#page2.tif	

CH \$40.00 12343341

500882867

PATENT
REEL: 022809 FRAME: 0435

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Rajasekaran SWAMINATHAN

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

ATTACHMENT USING MAGNETIC PARTICLE BASED SOLDER COMPOSITES

(I hereby authorize and request my attorney, associated with Customer Number 46915, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on 12/23/2008 as

United States Application Number 12/343,341 and


which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all

applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

CITY DATE	(1) at <u>Chandler, AZ</u> on <u>23rd December,</u> 2008	 Rajasekaran SWAMINATHAN	SIGNATURE INVENTOR
--------------	---	---	-----------------------